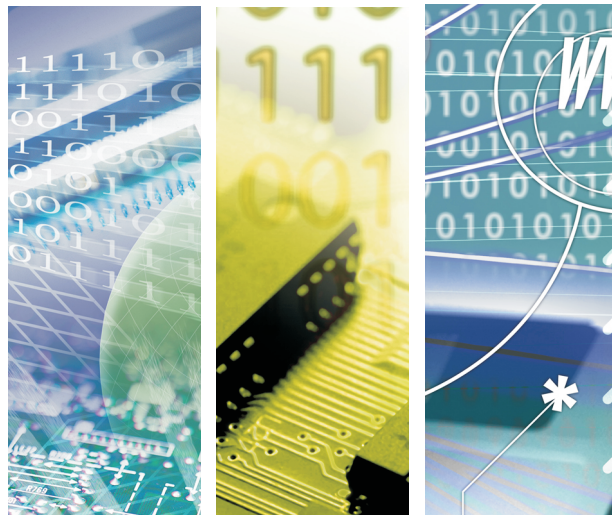
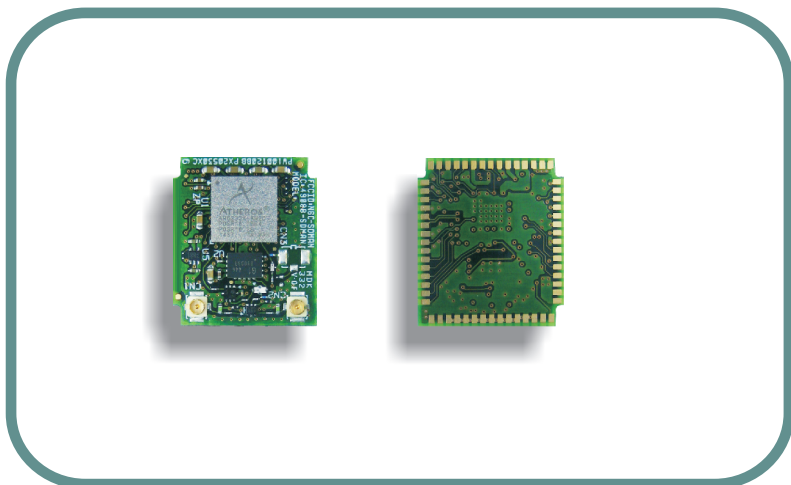




CFN905A

IEEE 802.11a/b/g/n Wi-Fi SiP Module



CFN905A

2.4GHz & 5GHz Dual Band IEEE802.11abgn, Bluetooth 4.0+LE Dual mode and SDIO2.0

Introduction of Products

Bointec CFN905A is the radio module which supports Dual Band IEEE802.11abgn, Bluetooth 4.0+LE Dual mode and SDIO2.0. The connection with the host board uses a board to board or direct solder mounting. This module complies with EU RoHS

Bointec CFN905A is made up of an AR6233 SiP module which contains a MAC/BBP chipset AR6003X (Qualcomm Atheros), 2.4GHz RF front end circuits and a 5GHz RF front end module. Also this module supports high speed 1x1 SISO and 40MHz band width mode for only 5GHz. Form factors are Surface mount version.

Bointec CFN905A is designed to be embedded into general electric devices. This module is a wireless device using the 2.4GHz / 5GHz band. You have to disable 5.15-5.35GHz band (W52, W53) for outdoor use in Japan because these band are prohibited to be used by low restriction.

Product Highlight

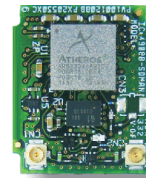
- *IEEE 802.11a/b/g/n conformity (2.4GHz & 5GHz)
- *Supports the single stream 1 x 1 SISO system and 40MHz band width for 5GHz. (Throughput up to 150Mbps)
- *Data rates of 1 - 54 Mbps for 802.11b/g, 6 - 54 Mbps for 802.11a and MCS0-6 for 802.11n.
- *Optionally supports Tx/Rx software selection diversity for Wireless LAN mode.
- *Supports Bluetooth 4.0+LE Dual mode
- *Supports TDMA WLAN / Bluetooth Coexistence (Optionally support FDMA without BT3.0+HS)
- *Supports SDIO 2.0 as the host IF of wireless LAN
- *Supports UART (up to 3Mbps) and USB (In the case driver supports USB) as the host IF of Bluetooth
- *Calibrates Tx power per module.
- *RoHS compliant



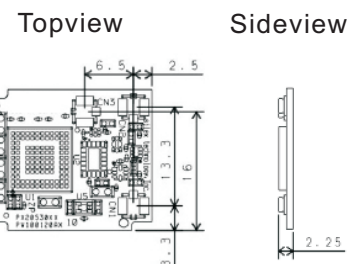
Specification

General specification		
Items		
Connector Type	SMT : 60 pins direct solder pads	
Antenna connectors	U.FL Alternative connector x 2	
Device Interfaces	SDIO v2.0 UART	
RF Interface	IEEE802.11a/b/g/n Bluetooth 4.0+LE Dual mode	
Weight	SMT version	1.4 +/- 0.1 g
Dimensions	SMT W x H x D	19mm x 22mm x 2.25mm
Hardware encryption engine	WLAN	RC4 128 bits AES 128 bits
	Bluetooth	E0 128bits AES 128 bits
Environmental specification		
Items		
Storage temperature	-20 to +85 °C	
Storage humidity	20 to 85 %RH	
Operating Temperature	-10 to +70 °C	
Operating humidity	20 to 80 %RH	
Wireless LAN Radio configuration and general specification		
Item		
Chipset	AR6233X, Core chip AR6003X CSP(Qualcomm Atheros)	
Center frequency	11a	5180 - 5825 (MHz)
	11na HT20	5180 - 5825 (MHz)
	11na HT40	5190 - 5795 (MHz)
	11b	2412 - 2472 (MHz)
	11g	2412 - 2472 (MHz)
	11ng HT20	2412 - 2472 (MHz)
Channel Spacing	11a/11naHT20	20 (MHz)
	11b/11g/11ng HT20/11ng HT40	5 (MHz)
	11na HT40	40 (MHz)
Rate	11b	1, 2, 5.5L, 5.5S, 11L, 11S (Mbps)
	11a/g	6, 9, 12, 18, 24, 36, 48, 54 (Mbps)
	11na/11ng 1Stream	MCS0, 1, 2, 3, 4, 5, 6, 7
Modulation type	11a/11na	OFDM(64QAM,16QAM,QPSK,BPSK)
	11b	DSSS(CCK,DQPSK,DBPSK)
	11g/11ng	DSSS-OFDM (64QAM,16QAM,QPSK,BPSK)
Bluetooth Radio configuration and general specification		
Item		
Chipset	AR6233X, Core chip AR3002X CSP (Qualcomm Atheros)	
Center frequency	2402 – 2480 (MHz)	
Channel Spacing	1.x/2.x/3.x	Ch.1 – Ch.79 (1MHz)
	4.x	Ch.0 – Ch.39 (2MHz)
Modulation type	π/4 DQPSK (2Mbps) 8DQPSK (3Mbps) GFSK (1Mbps)	
Packet type	Common	NULL, POLL, FHS
	AQL	EV4, EV5, 2EV3, 2EV5, 3EV3, 3EV5 HV1, HV2, HV3, EV3
	SCO	DM1, DM3, DM5, AUX1, DH1, DH3, DH5, 2DH1, 2DH3, 2DH5, 3DH1, 3DH3, 3DH5

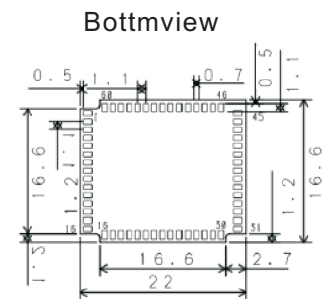
Product quick glance



ME Drawing/placement



ME Drawing/placement



We are Your Partner more than Business



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